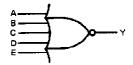
- Package Options Include Ceramic Chip Carriers and Flat Packages in Addition to Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

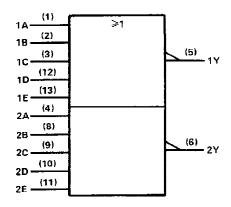
These devices contain two independent 5-input positive  $\neg NOR$  gates. They perform the Boolean function Y = A + B + C + D + E in positive logic.

The SN54S260 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74S260 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

#### logic diagram (each gate)

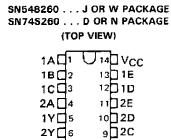


#### logic symbol†



<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

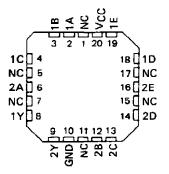
Pin numbers shown are for D, J, N, and W packages.



SN54S260 . . . FK PACKAGE (TOP VIEW)

GND 7

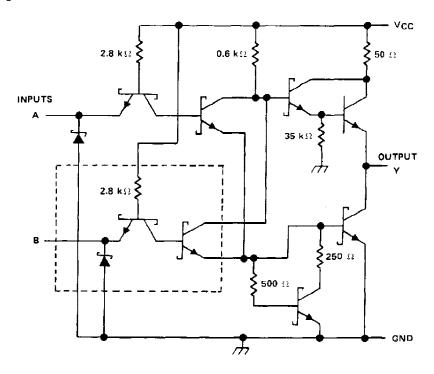
8 2B



NC - No internal connection

## SN54S260, SN74S260 DUAL 5-INPUT POSITIVE-NOR GATES

### schematic (each gate)



Resistor values shown are nominal.

The portion of the schematic within the deshed-line is repeated for each additional input.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
	•, ••••••••••••••	
Operating free-air temperature range:	SN54'	- 55°C to 125°C
-	SN74'	0°C to 70°C
	•••••	

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN54S260			SN74S260			
	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
V <sub>IH</sub> High-level input voltage	2			_2			V	
VIL Low-level input voltage			8.0			8.0	V	
IOH High-level autput current			<b>–</b> 1			- 1	mA	
IOL Low-level output current			20			20	mA	
TA Operating free-air temperature	<b>– 55</b>		125	0		70	°C	

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			N54S26	0	s	UNIT				
PARAMETER		TEST CONDITIONS †				MAX	MIN	TYP <sup>‡</sup>	MAX	UNII
VIK	VCC = MIN,	I <sub>I</sub> = 18 mA				-1.2			-1.2	V
VOH	V <sub>CC</sub> = MIN,	V <sub>1L</sub> = 0.8 V,	I <sub>OH</sub> = 1 mA	2.5	3.4		2.7	3.4		V
VOL	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 20 mA			0.5			0.5	V
- I <sub>I</sub>	VCC = MAX.	V <sub>1</sub> = 5.5 V				1			1	mA
lін	V <sub>CC</sub> = MAX,	V <sub>IH</sub> = 2.7 V				50			50	μА
11L	V <sub>CC</sub> = MAX,	V <sub>IL</sub> = 0.5 V				<b>– 2</b>			<u>-2</u>	mA
IOS§	V <sub>CC</sub> = MAX			- 40		- 100	-40	_	- 100	mΑ
<sup>I</sup> ссн	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0 V			17	29		17	29	mΑ
<sup>1</sup> CCL	V <sub>CC</sub> = MAX,	See Note 2			26	45		26	45	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 3)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP	MAX	UNIT
ſ	<sup>t</sup> PLH	Any		$R_1 = 280 \Omega$ , $C_1 = 15 pF$	4	5.5	ns .
	tpHL	Any	,	N[-280 %; C[-15 PF	4	6	пs

NOTE 3: See General Information Section for load circuits and voltage waveforms.

<sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second. NOTE 2: One input at 4.5 V, all others at GND.

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN54S260J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54S260J
SN54S260J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54S260J
SN74S260D	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	0 to 70	S260
SN74S260DR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	S260
SN74S260DR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	S260
SN74S260N	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74S260N
SN74S260N.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74S260N
SNJ54S260J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260J
SNJ54S260J.A	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260J
SNJ54S260W	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260W
SNJ54S260W.A	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54S260W

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54S260, SN74S260:

Catalog: SN74S260

Military: SN54S260

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74S260DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74S260DR	SOIC	D	14	2500	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74S260N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74S260N.A	N	PDIP	14	25	506	13.97	11230	4.32

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SMALL OUTLINE INTEGRATED CIRCUIT



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



# W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



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